

ABSTRACT

HOLLOW PACKAGE AND METHOD FOR MANUFACTURING SAME

A hollow package (103) includes a substrate (109), an element (111), a partition wall (113), and a top plate (115) and has one or more closed hollow parts (117) that are covered by the substrate (109), the partition wall (113), and the top plate (115), and the substrate (109), the partition wall (113), and the top plate (115) are sealed with a cured product of a sealing resin composition. The top plate (115) and the partition wall (113) are composed of an organic material, and the thickness of the top plate (115), the thickness of the partition wall (113), the width of the partition wall, and the maximum width of the hollow part (117) are each within respective predetermined ranges. The sealing resin composition comprises (A) an epoxy resin that includes one or more selected from the group consisting of an epoxy resin containing two epoxy groups in the molecule and an epoxy resin containing three or more epoxy resins in the molecule and (B) an inorganic filler.

FIG. 1